



Material Content Data Sheet



Sales Product Name		IPD50N08S4-13		Issued		4. July 2019		
MA#		MA003587326						
Package		PG-TO252-3-313		Weight*		317.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.872	0.59	0.59	5888	5888
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.27	46.33	462690	463292
	non noble metal	aluminium	7429-90-5	2.328	0.73	0.73	7322	7322
wire	non noble metal	aluminium	7429-90-5	2.328	0.73	0.73	7322	7322
encapsulation	organic material	carbon black	1333-86-4	1.402	0.44		4410	
	plastics	epoxy resin	-	24.536	7.72		77179	
	inorganic material	silicondioxide	60676-86-0	114.270	35.94	44.10	359435	441024
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11764	11764
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4468	4479
solder	non noble metal	tin	7440-31-5	0.037	0.01		117	
	noble metal	silver	7440-22-4	0.046	0.01		146	
	non noble metal	lead	7439-92-1	1.770	0.56	0.58	5567	5830
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60323	60401
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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